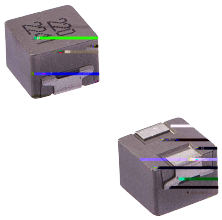
MDA HT Series

SMD Low Profile High Current Molded Inductor

Size 8054



FEATURES

- Low loss realized with low DCR.
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- 100% Lead(Pb)-Free and RoHS compliant.
- High performance (Isat) realized by metal dust core.
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APPLICATION

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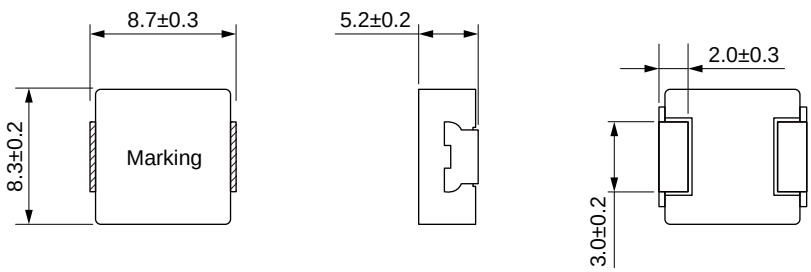
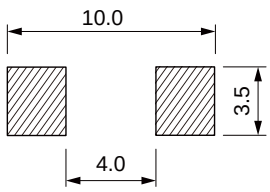
- HVAC
- 5ƨ2ŃăƩ ǿƛƴŘ2ǿ fƛD l·ƴŘ ăŜl·ű Ŏ2ƴűŃ2f
- Audio subsystem
- Digital instrument cluster
- Lƴπ±ŜKƛŎfŜ LƴŦ2űl·ƛƴƴŜƴű l·ƴŘ ƴl·ǾƛƎl·ə2ƴ

Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Current Typ. (A)	Current Max. (A)	DC Resistance Typ.	DC Resistance Max.
±20%	15.5	14.0	22.0	19.0	4.0	4.8
±20%	14.5	13.0	18.0	15.5	6.5	7.8
±20%	13.5	12.5	16.3	14.0	9.5	11.4
±20%	11.0	10.0	12.0	11.0	13.0	15.6
±20%	11.0	9.0	15.0	13.0	18.0	22.0
±20%	7.8	6.8	9.0	7.7	29.0	35.0
±20%	6.0	5.5	7.8	6.7	44.0	52.8
±20%	5.5	5.0	7.2	6.2	56.0	67.0
±20%	3.5	3.0	5.2	4.5	122	135

Temperature Rise Current: The actual value of DC current when the temperature rise i

Typical Electrical Characteristics:

Soldering Reflow:

Preheat condition: 150 ~200℃/ 60~120 sec.

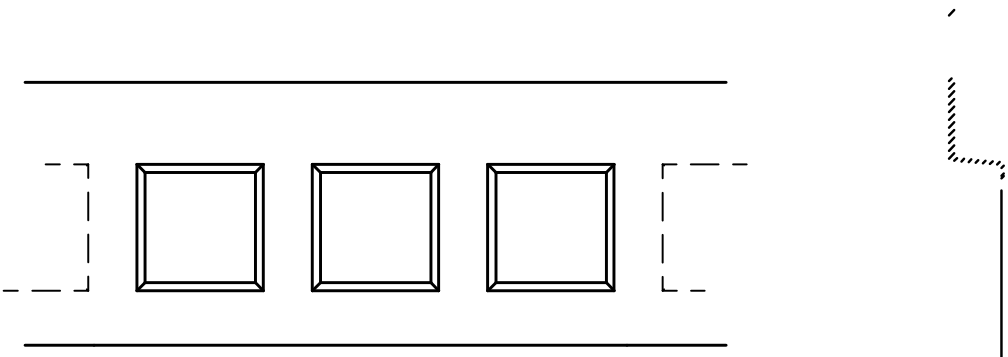
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Allowed Reflow time: 2x max.P1

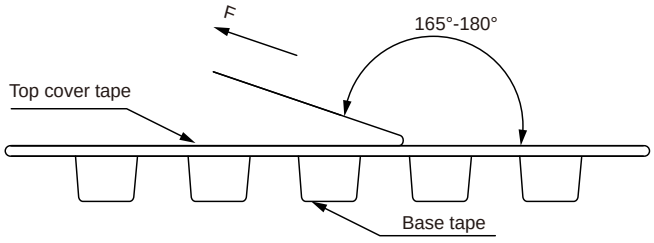
Packaging Information:

Tape Dimension:



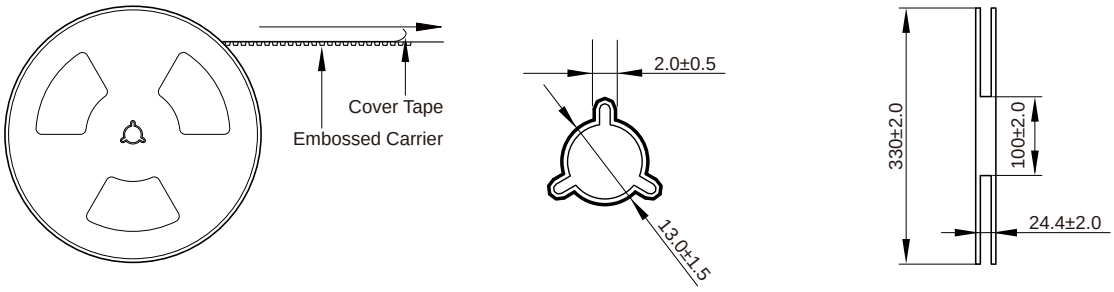
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	T (mm)
MDA8054HT	8.9±0.1	9.0±0.1	1.5±0.1	4.0±0.1	16.0±0.1	24.0±0.3	5.9±0.1	0.40±0.05

Peel force of top cover tape:

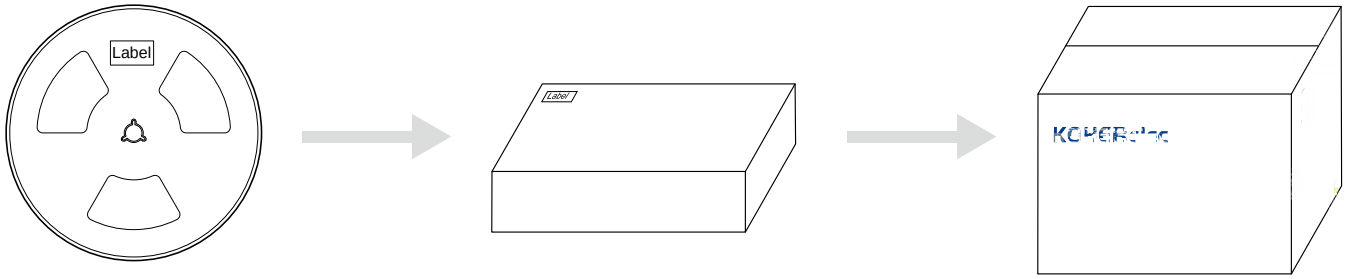


The peel force of top cover tape shall be between 0.1 to 1.27 N

Reel Dimension：[mm]



Packaging Quantity:



500 Pcs/Reel

2 Reel /Inner box(1000 Pcs)

3 Inner box/Carton box(3K Pcs)

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.